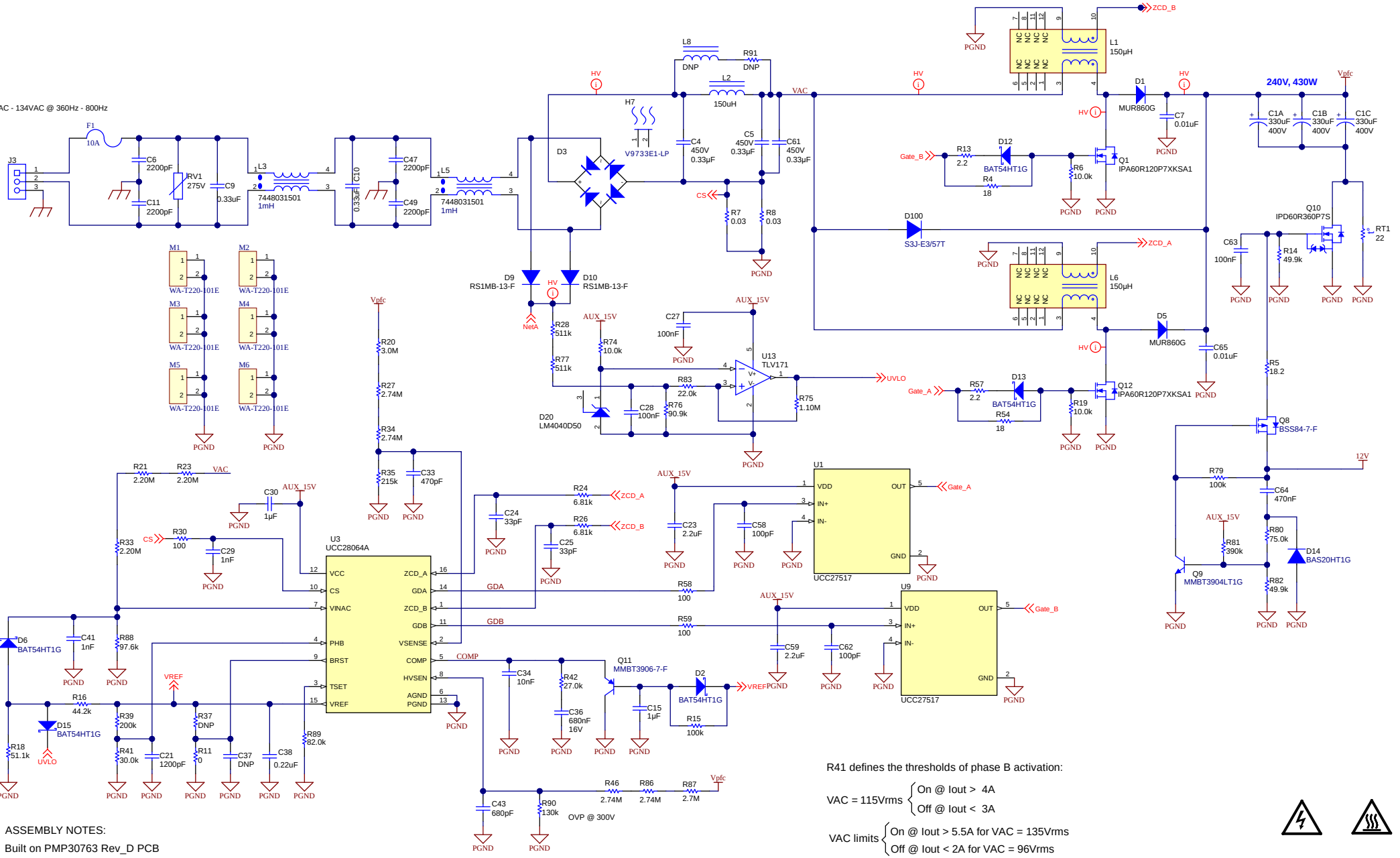


R41 defines the thresholds of phase B activation:

VAC = 115Vrms { On @ Iout > 4A / Off @ Iout < 3A

VAC limits { On @ Iout > 5.5A for VAC = 135Vrms / Off @ Iout < 2A for VAC = 96Vrms

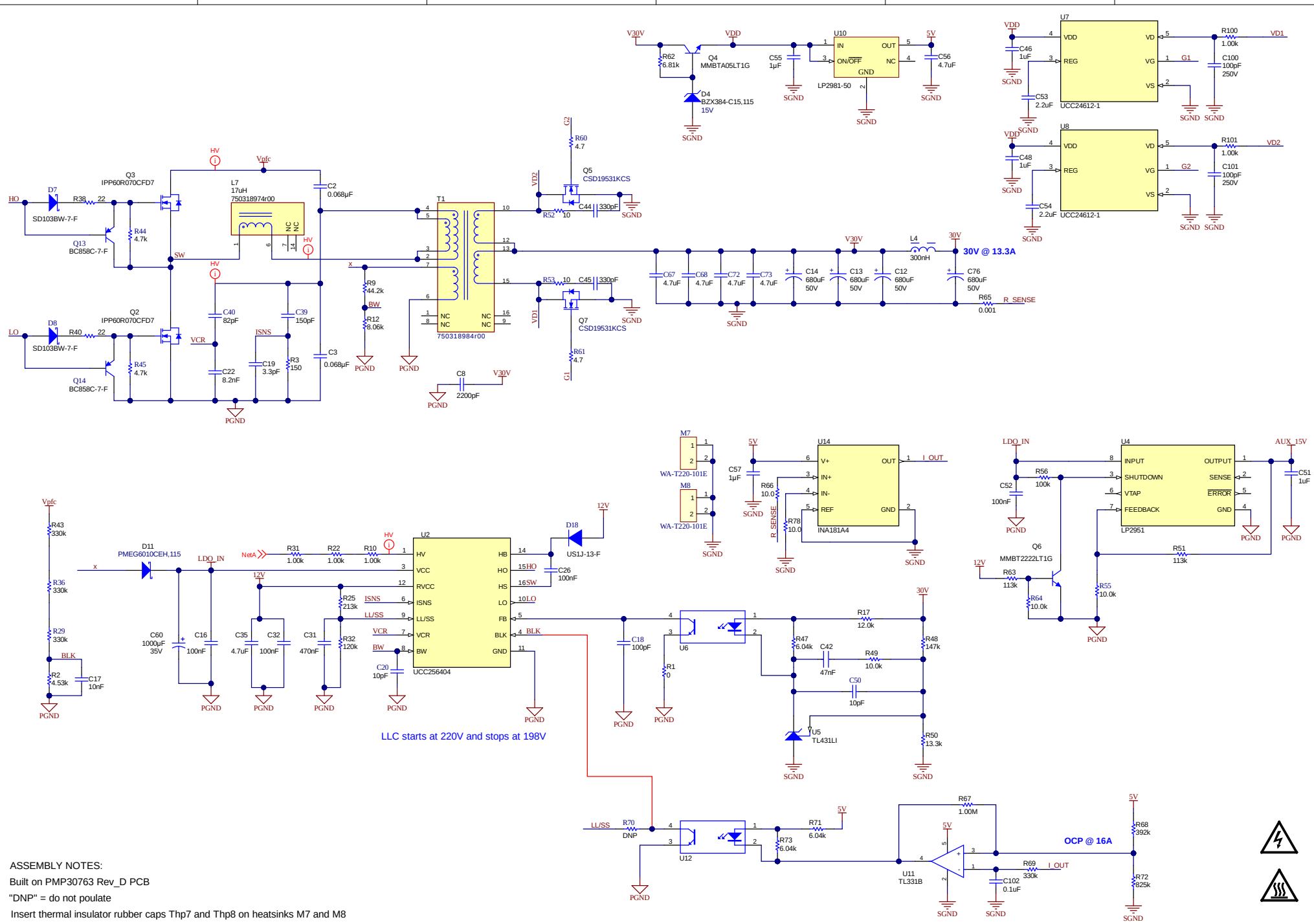
ASSEMBLY NOTES:

Built on PMP30763 Rev_D PCB

"DNP" = do not poulate

Insert thermal insulator rubber caps Thp1....6 on heatsinks M1....M6

Orderable: N/A	Designed for: Public Release	Mod. Date: 24/05/2022
TID #:	Project Title: 400W, PFC + LLC for Avionics	
Number: PMP31179 Rev: A	Sheet Title: PFC	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 1 of 3
Drawn By: R. Scibilia	File: PMP31179 Rev_A PFC Schematic.SchDoc	Size: B
Engineer: R. Scibilia	Contact: http://www.ti.com/support	http://www.ti.com



ASSEMBLY NOTES:

Built on PMP30763 Rev_D PCB

"DNP" = do not poulate

Insert thermal insulator rubber caps Thp7 and Thp8 on heatsinks M7 and M8

Connect pin 4 of U12 with pin 4 of U2 (net BLK)

Add C102 between pins 1 and 2 of U11

Orderable: N/A	Designed for: Public Release	Mod. Date: 24/05/2022	
TID #:	Project Title: 400W, PFC + LLC for Avionics		
Number: PMP31179 Rev: A	Sheet Title: LLC		
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 2 of 3	
Drawn By: R. Scibilia	File: PMP31179 Rev_A LLC Schematic.SchDoc	Size: B	
Engineer: R. Scibilia	Contact: http://www.ti.com/support		

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H1 Bumpon

H2 Bumpon

H3 Bumpon

H4 Bumpon

H5 Bumpon

H6 Bumpon

Thp1 MECH Thermal pad

Thp2 MECH Thermal pad

Thp3 MECH Thermal pad

Thp4 MECH Thermal pad

Thp5 MECH Thermal pad

Thp6 MECH Thermal pad

Thp7 MECH Thermal pad

Thp8 MECH Thermal pad

PCB
LOGO

LOGO4 LOGO10 LOGO7 LOGO8 LOGO3 LOGO9

Orderable: N/A		Designed for: Public Release	Mod. Date: 10/05/2022
TID #:		Project Title: 400W, PFC + LLC for Avionics	
Number: PMP31179	Rev: A	Sheet Title: Hardware	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 3 of 3
Drawn By: R. Scibilia		File: PMP31179 Rev_A Hardware.SchDoc	Size: B
Engineer: R. Scibilia		Contact: http://www.ti.com/support	

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